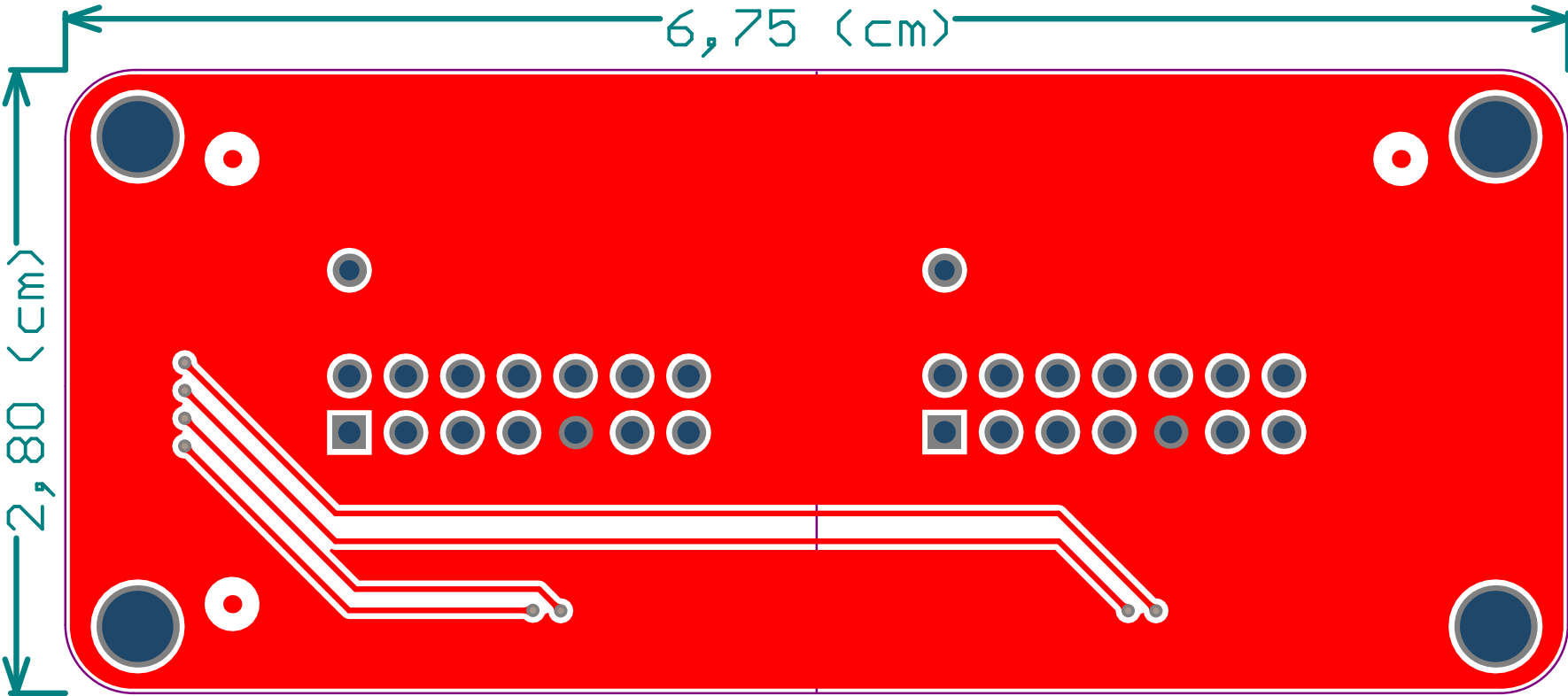
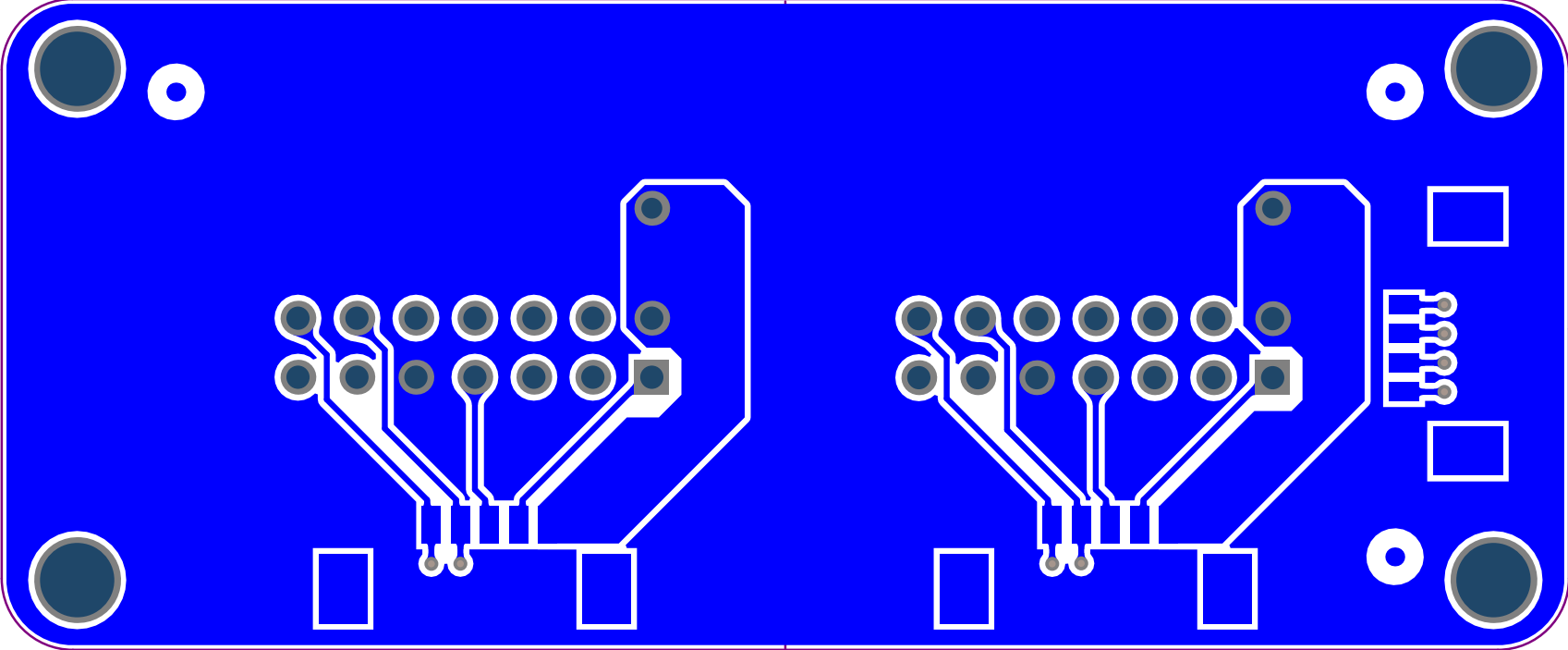


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,036mm		
4	Dielectric 1	FR-4	1,500mm	4,8	
5	Bottom Layer	Copper	0,036mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				



TITLE: SEMI USB N.2 BOARD		REV:1.0	DATE: DD/MM/2020
MATERIAL:FR4	Silkscreen color: white	Project: IIP FloripaSat-2	
Board Tickness: 1.6mm	Layers: 02	Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC	
PCB Surface: ENIG	Drawing: Yan C. de Azeredo		



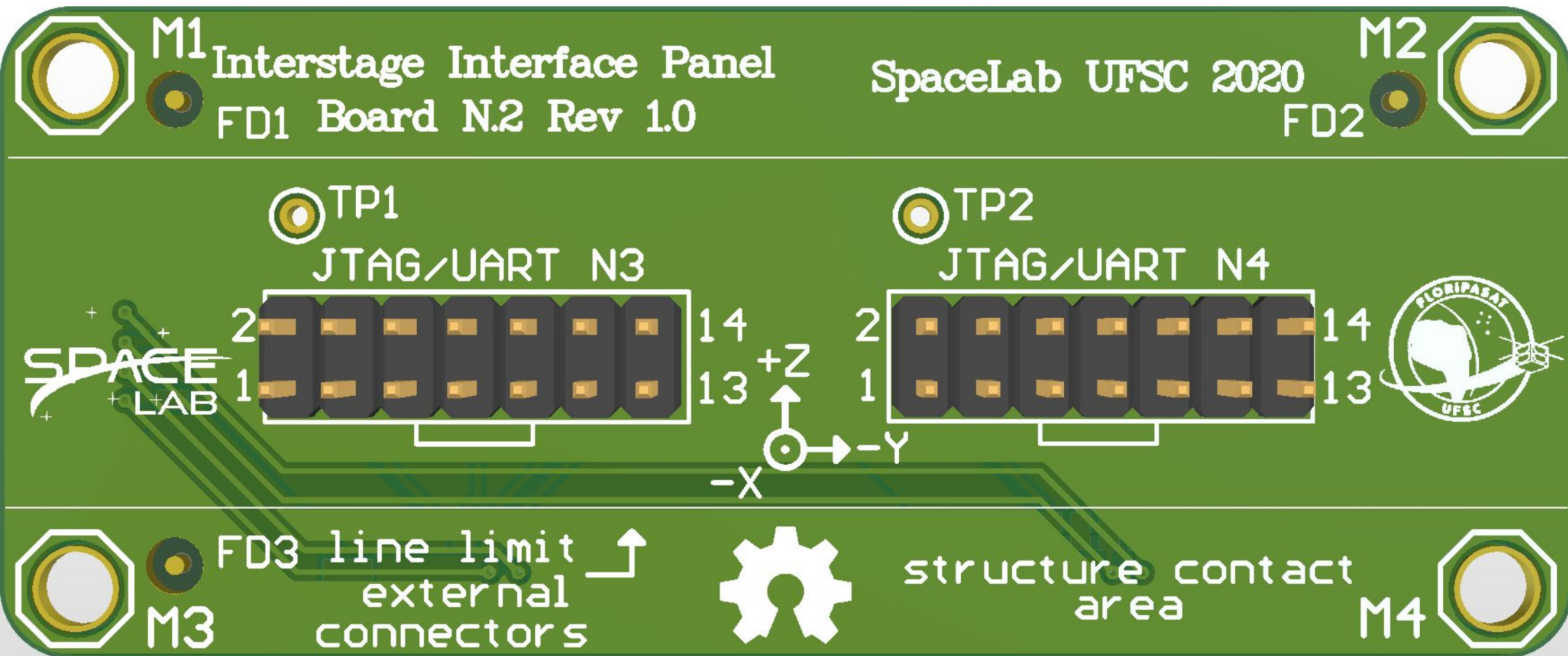
CN1
+

CN4
+

CN5₊

CN3₊

CN2₊



M2

SpaceLab UFSC 2020

Interstage Interface Panel

Board N.2 Rev 1.0

M1

TP2

CN4

14

13

GND TCK

GND Rx4 Tx4 TDO VCC

VCC

2

1

CN5
JTAG4

+Z
+X
-Y

M4

TP1

CN1

14

13

GND TCK

GND Rx3 Tx3 TDO VCC

VCC

2

1

CN3
JTAG3

M3

CN2

UART
FT4232H
GND
Rx4 Tx4
Rx3 Tx3